



SE05NRE14GA

Feature

u Transient protection for high-speed data lines
IEC 61000-4-2 (ESD) ±25kV (Air)

±17kV (Contact)

IEC 61000-4-4 (EFT) 40A (5/50 ns) Cable Discharge Event (CDE)

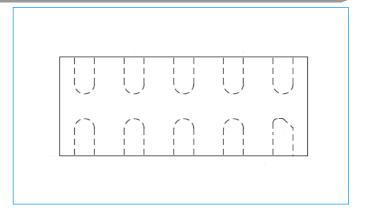
- u Package optimized for high-speed lines
- **u** Ultra-small package (2.5mm x1.0mm x 0.55mm)
- u Protects four data lines
- u Low capacitance: 0.6pF for each channel
- u Low leakage current: 0.1µA @ V_{RWM}(Typical)
- u Low clamping voltage
- Each I/O pin can withstand over 1000 ESD strikes for ±8kV contact discharge

Applications

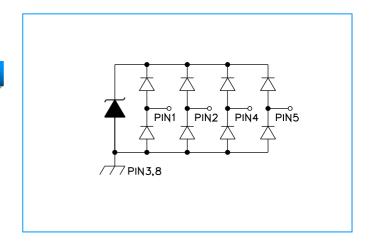
- u Serial ATA
- u PCI Express
- Desktops, Servers and Notebooks
- u MDDI Ports
- u USB 2.0/3.0 Power and Data Line Protection
- u Display Ports
- u High Definition Multi-Media Interface (HDMI)
- u Digital Visual Interfaces (DVI)

Mechanical Characteristics

- u DFN-10L package
- u Flammability Rating: UL 94V-0
- u Marking: Part number
- u Packaging: Tape and ReeL



Pin Configuration







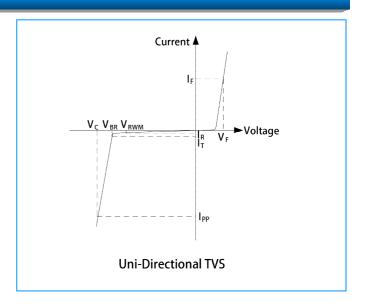
SE05NRE14GA

Absolute Maximum Rating

Symbol	Parameter	Value	Units	
V _{ESD}	ESD per IEC 61000-4-2 (Air)	±25	KV	
	ESD per IEC 61000-4-2 (Contact)	±17		
T _{OPT}	Operating Temperature	-55/+125	°C	
T _{STG} Storage Temperature		-55/+150	°C	

Electrical Characteristics (T=25℃)

Symbol	Parameter	
V_{RWM}	Nominal Reverse Working Voltage	
I_R	Reverse Leakage Current @ V _{RWM}	
V_{BR}	Reverse Breakdown Voltage @ I _T	
I_{T}	Test Current for Reverse Breakdown	
$V_{\rm C}$	Clamping Voltage @ IPP	
I_{PP}	Maximum Peak Pulse Current	
C _J	Parasitic Capacitance	
V_R	Reverse Voltage	
f	Small Signal Frequency	
I_{F}	Forward Current	
V_{F}	Forward Voltage @ I _F	



Symbol	Test Condition	Minimum	Typical	Maximum	Units
V _{RWM}				5.0	V
I _R	V _{RWM} = 5V, T = 25℃ Between I/O and GND		0.1	1.0	μΑ
V _{BR}	$I_T = 1 \text{mA}$ Between I/O and GND	6.0	8.0	10.0	V
Vc	I _{PP} = 4A, tp = 8/20µs Between I/O and GND		12	15	V
CJ	$V_R = 0V$, $f = 1MHz$ Between I/O and GND		0.6	0.8	pF
Сл	$V_R = 0V$, $f = 1MHz$ Between I/O and I/O		0.3	0.4	pF

Electrical Characteristics (T=25℃)

SOCAY Electronics Co., Ltd.

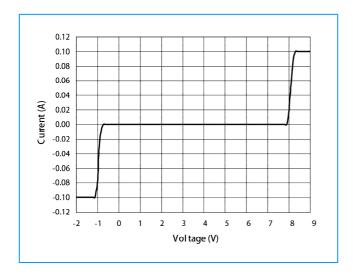
www.socay.com



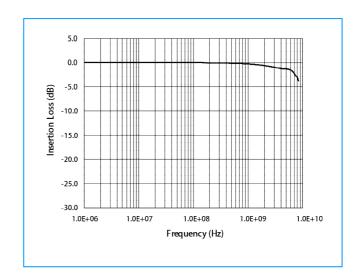


SE05NRE14GA

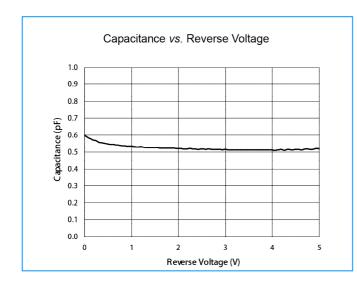
Voltage Sweeping of I/O to GND

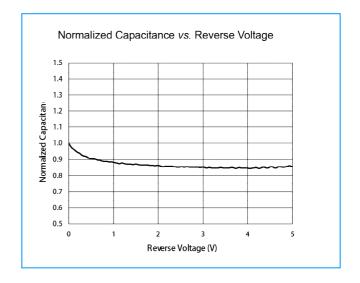


Insertion Loss S21 of I/O to GND



Capacitance vs . Voltage of I/O to GND (f=1MHz)





ESD Clamping of I/O to GND

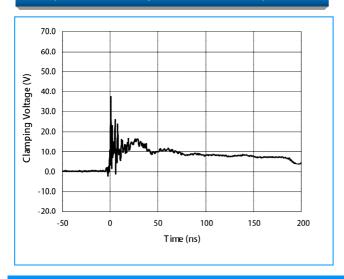
ESD Clamping of I/O to GND



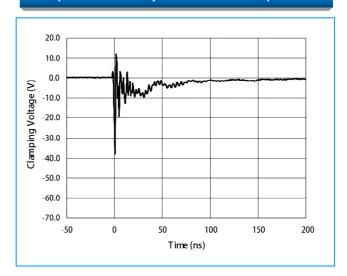


SE05NRE14GA

(+8KV Contact per IEC 61000- 4-2)



(- 8KV Contact per IEC 61000- 4-2)



Application Information

Pin Connection in PCB

SE05NE14GA provides ESD protection for four data

lines simultaneously . The pin connection is shown in the figure below.

Four parallel data lines, from inner IC to I/O port connector, could connect to SE05NE14GA four I/O pins directly.Pin3&8 of SE05NE14GA is theGND pin, which should connect to the GND of PCB. The wire should be as short as possible in order to minimize the parasitic inductance.

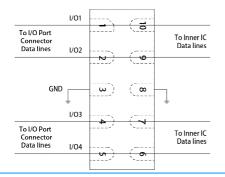


Figure 15E05NRA14 pin connection in PCB

PCB Layout Guidelines

For optimum ESD protection and the whole circuit performance, the following PCB layout guidelines are recommended:

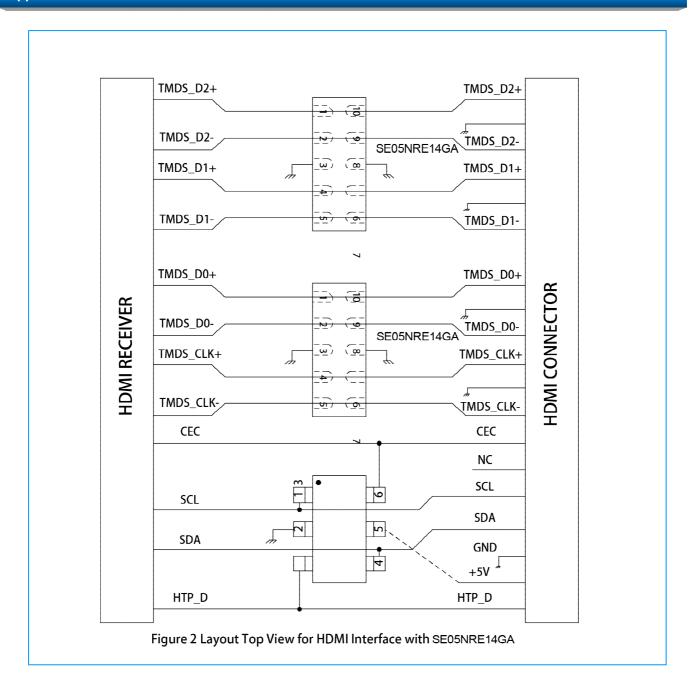
- SE05NE14GA GND pin to the PCB GND rail path
 - should be as short as possible. It could reduce the ESD transient return path to GND.
- U The vias connecting SE05NE14GA GND pins to The PCB GND should be wide
- Place SE05NE14GA as close to the connector port as possible. It could reduce the parasiti inductance
 - and restrict ESD coupling into adjacent traces.
- **u** Avoid running critical signals near board edges





SE05NRE14GA

Application Information



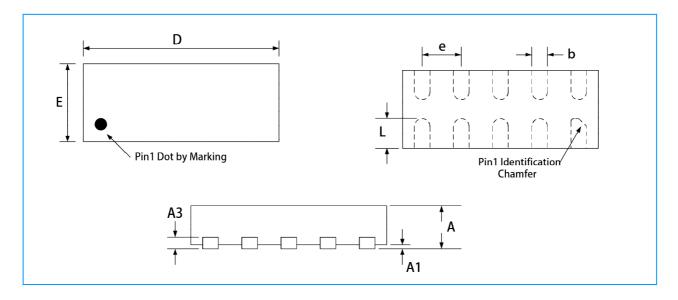




SE05NRE14GA

Package Outline

- u DFN-10L package
- Thermally-Enhanced
- **u** MSL-1 Level



Package Dimensions (Controlling dimensions are in millimeters)

Cymbol	Dimensions (mm)		Dimensions (Inches)	
Symbol	Minimum	Maximum	Minimum	Maximum
A	0.500	0.600	0.020	0.024
A1	0.000	0.050	0.000	0.002
A3	0.15REF.		0.006REF.	
b	0.150	0.250	0.006	0.010
D	2.450	2.550	0.096	0.100
Е	0.950	1.050	0.037	0.041
e	0.500REF.		0.020REF.	
L	0.300	0.400	0.012	0.016